



Material Content Data Sheet



Sales Product Name		BAS 70-06W H6327		Issued		29. August 2013		
MA#		MA000845644						
Package		PG-SOT323-3-1		Weight*		5.96 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	arsenic	7440-38-2	0.000	0.00		10	
	noble metal	gold	7440-57-5	0.006	0.10		1005	
	inorganic material	silicon	7440-21-3	0.051	0.86	0.96	8579	9594
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		88	
	non noble metal	titanium	7440-32-6	0.003	0.04		441	
	non noble metal	chromium	7440-47-3	0.008	0.13		1322	
	non noble metal	copper	7440-50-8	2.617	43.90	44.08	438956	440807
wire	non noble metal	copper	7440-50-8	0.004	0.07	0.07	722	722
encapsulation	organic material	carbon black	1333-86-4	0.031	0.52		5249	
	plastics	epoxy resin	-	0.673	11.29		112862	
	inorganic material	silicondioxide	60676-86-0	2.425	40.68	52.49	406828	524939
leadfinish	non noble metal	tin	7440-31-5	0.133	2.23	2.23	22259	22259
plating	noble metal	silver	7440-22-4	0.010	0.17	0.17	1679	1679
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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